



Foshan city Hexin semiconductor Co., Ltd.

## 12N65

N-Channel Power MOSFET

$V_{(BR)DSS}$	$R_{DS(on)}\text{MAX}$	$I_D$
650V	0.85Ω@10V	12A

### GENERAL DESCRIPTION

This advanced high voltage MOSFET is designed to stand high energy in the avalanche mode and switch efficiently. This new high energy device also offers a drain-to-source diode fast recovery time. Designed for high voltage, high speed switching applications such as power supplies, converters, power motor controls and bridge circuits.

### FEATURE

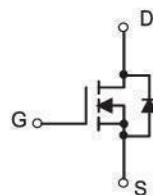
- High Current Rating
- Lower  $R_{DS(on)}$
- Low Reverse Transfer Capacitance
- Fast Switching Capability
- Tighter  $V_{SD}$  Specifications
- Avalanche Energy Specified

T0-220F

1. GATE
2. DRAIN
3. SOURCE



### Equivalent Circuit



### Maximum ratings ( $T_a=25^\circ\text{C}$ unless otherwise noted)

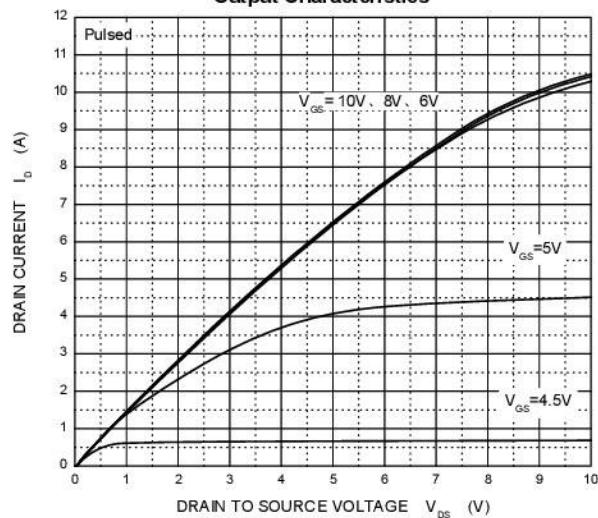
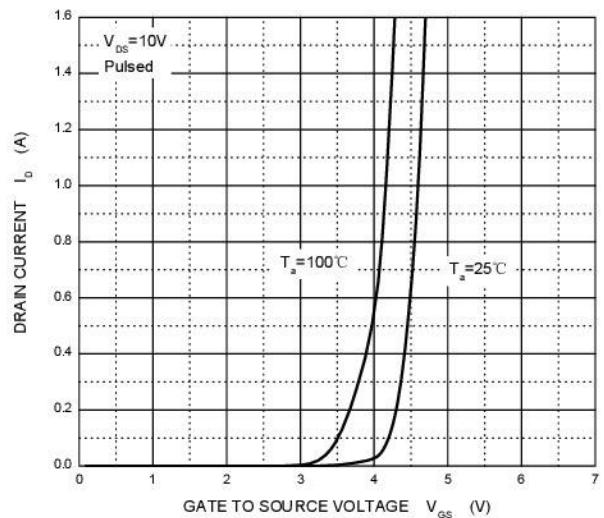
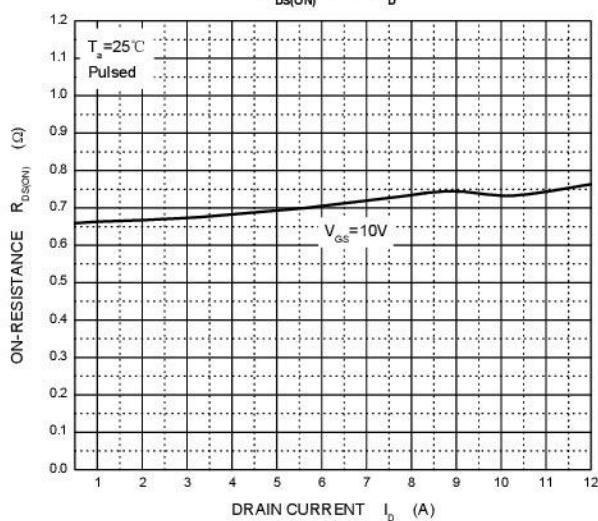
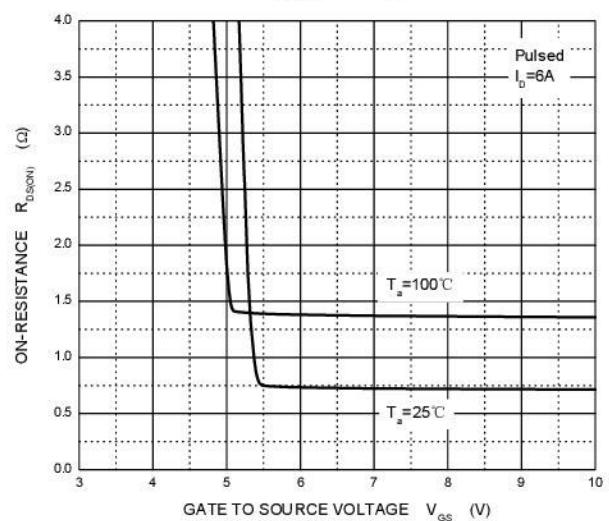
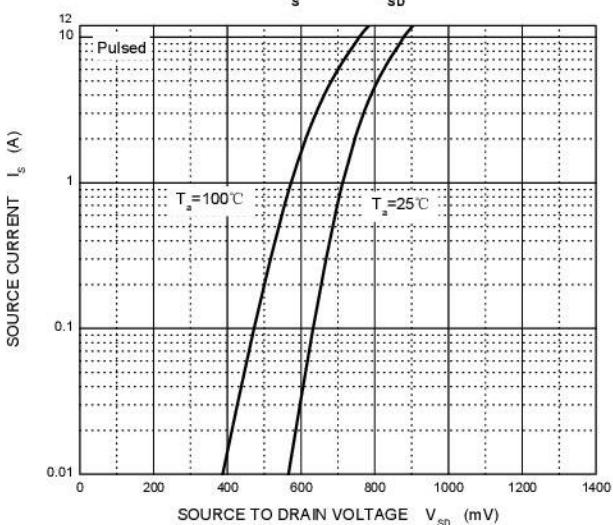
Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	650	V
Gate-Source Voltage	$V_{GSS}$	$\pm 30$	
Continuous Drain Current	$I_D$	12	A
Pulsed Drain Current(note1)	$I_{DM}$	48	
Single Pulsed Avalanche Energy (note2)	$E_{AS}$	540	mJ
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	62.5	°C/W
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 ~+150	°C
Maximum lead temperature for soldering purposes , 1/8"from case for 5 seconds	$T_L$	260	

$T_a=25^\circ\text{C}$  unless otherwise specified

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Off characteristics</b>						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	650			V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 650\text{V}, V_{GS} = 0\text{V}$			1	$\mu\text{A}$
Gate-body leakage current (note3)	$I_{GSS}$	$V_{DS} = 0\text{V}, V_{GS} = \pm 30\text{V}$			$\pm 100$	$\text{nA}$
<b>On characteristics (note3)</b>						
Gate-threshold voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.0	3.5	4.0	V
Static drain-source on-resistance	$R_{DS(\text{on})}$	$V_{GS} = 10\text{V}, I_D = 6\text{A}$		0.7	0.85	$\Omega$
<b>Dynamic characteristics (note 4)</b>						
Input capacitance	$C_{iss}$	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$		1800		pF
Output capacitance	$C_{oss}$			200		
Reverse transfer capacitance	$C_{rss}$			25		
<b>Switching characteristics (note1,3 4)</b>						
Total gate charge	$Q_g$	$V_{DS} = 520\text{V}, V_{GS} = 10\text{V}, I_D = 12\text{A}$		42	54	nC
Gate-source charge	$Q_{gs}$			8.6		
Gate-drain charge	$Q_{gd}$			21		
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 325\text{V}, V_{GS} = 10\text{V}, R_G = 25\Omega, I_D = 12\text{A}$		30		ns
Turn-on rise time	$t_r$			90		
Turn-off delay time	$t_{d(off)}$			160		
Turn-off fall time	$t_f$			90		
<b>Drain-Source Diode Characteristics</b>						
Drain-source diode forward voltage(note3)	$V_{SD}$	$V_{GS} = 0\text{V}, I_S = 12\text{A}$			1.4	V
Maximum continuous drain-source diode forward current	$I_S$				12	A
Maximum pulsed drain-source diode forward current	$I_{SM}$				48	A

#### Notes :

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2.  $L = 7.5\text{mH}, I_{AS} = 12\text{A}, V_{DD} = 50\text{V}, R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$
3. Pulse Test : Pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
4. These parameters have no way to verify.

**Output Characteristics****Transfer Characteristics** $R_{DS(ON)}$  —  $I_D$  $R_{DS(ON)}$  —  $V_{GS}$  $I_s$  —  $V_{SD}$ **Threshold Voltage**